

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOSII)

TPC8003

Lithium Ion Battery Applications Portable Equipment Applications Notebook PC Applications

• Small footprint due to small and thin package

• Low drain-source ON resistance : RDS (ON) = $5.4 \text{ m}\Omega$ (typ.)

 $\bullet~$ High forward transfer admittance : $|\,Y_{fs}\,|\,$ = 21 S (typ.)

• Low leakage current : $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 30 \text{ V)}$

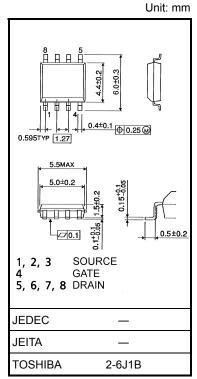
• Enhancement mode : $V_{th} = 0.8 \sim 2.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

| Characte | ristics | Symbol | Rating | Unit | |
|------------------------|-----------------------------|------------------|------------|------|--|
| Drain-source voltage | | V_{DSS} | 30 | V | |
| Drain-gate voltage (R | k _{GS} = 20 kΩ) | V_{DGR} | 30 | V | |
| Gate-source voltage | | V_{GSS} | ±20 | ٧ | |
| Drain current | DC (Note 1) | I _D | 13 | А | |
| Diam current | Pulse (Note 1) | I_{DP} | 52 | | |
| Drain power dissipati | on (t = 10 s) (Note 2a) | P_{D} | 2.4 | W | |
| Drain power dissipati | on (t = 10 s) (Note 2b) | P_{D} | 1.0 | W | |
| Single pulse avalance | ne energy (Note 3) | E _{AS} | 220 | mJ | |
| Avalanche current | | I _{AR} | 13 | Α | |
| Repetitive avalanche (| energy Note 2a) (Note 4) | E _{AR} | 0.24 | mJ | |
| Channel temperature | | T _{ch} | 150 | °C | |
| Storage temperature | range | T _{stg} | -55 to 150 | °C | |

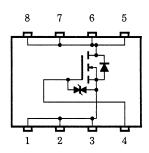
Note 1, Note 2, Note 3 and Note 4: See the next page.

This transistor is an electrostatic-sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

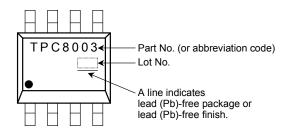
Circuit Configuration



Thermal Characteristics

| Characteristics | Symbol | Max | Unit |
|---|------------------------|------|------|
| Thermal resistance, channel to ambient (t = 10 s) (Note 2a) | R _{th (ch-a)} | 52.1 | °C/W |
| Thermal resistance, channel to ambient (t = 10 s) (Note 2b) | R _{th (ch-a)} | 125 | °C/W |

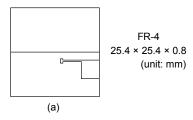
Marking (Note 5)

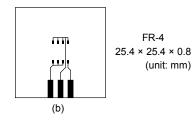


Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



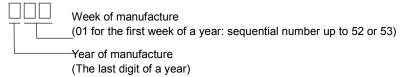


Note 3: V_{DD} = 24 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 13 A

Note 4: Reptitve rating: pulse width limited by maximum channel temperature

Note 5: ● on lower left of the marking indicates Pin 1.

Weekly code: (Three digits)



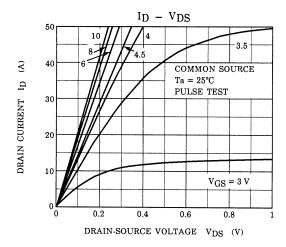
Electrical Characteristics (Ta = 25°C)

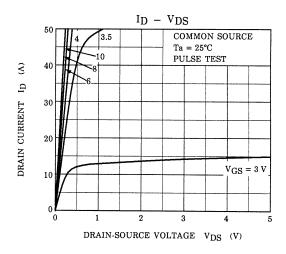
| Chara | cteristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|---|------------------------------|-----------------------|---|------|------|-----|------|
| Gate leakage cu | urrent | I _{GSS} | V _{GS} = ±16 V, V _{DS} = 0 V | _ | _ | ±10 | μA |
| Drain cut-off cu | rrent | I _{DSS} | V _{DS} = 30 V, V _{GS} = 0 V | _ | _ | 10 | μΑ |
| Drain-source breakdown voltage | | V _{(BR) DSS} | I _D = 10 mA, V _{GS} = 0 V | 30 | _ | _ | V |
| | | V (BR) DSX | I _D = 10 mA, V _{GS} = -20 V | 15 | _ | _ | V |
| Gate threshold | voltage | V_{th} | V _{DS} = 10 V, I _D = 1 mA | 0.8 | _ | 2.5 | V |
| Drain-source ON resistance | | R _{DS (ON)} | V _{GS} = 4 V, I _D = 6.5 A | _ | 8.3 | 13 | mΩ |
| | | R _{DS (ON)} | V _{GS} = 10 V, I _D = 6.5 A | _ | 5.4 | 7 | mΩ |
| Forward transfe | r admittance | Y _{fs} | V _{DS} = 10 V, I _D = 6.5 A | 10.5 | 21 | _ | S |
| Input capacitano | capacitance C _{iss} | | _ | 4380 | _ | | |
| Reverse transfer capacitance | | C _{rss} | V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz | _ | 500 | _ | pF |
| Output capacitance | | Coss | | _ | 890 | _ | |
| Switching time | Rise time | tr | $V_{GS} \stackrel{10 \text{ V}}{_{0 \text{ V}}} \stackrel{I_{D} = 6.5 \text{ A}}{\underset{\text{V}}{_{OUT}}} \\ V_{CI} \stackrel{\text{C}}{\underset{\text{V}}{_{W}}} \stackrel{\text{C}}{\underset{\text{V}}{_{W}}} = 15 \text{ V}$ $Duty \leq 1\%, \ t_{W} = 10 \ \mu\text{s}$ | _ | 14 | _ | |
| | Turn-on time | t _{on} | | l | 27 | ı | ns |
| | Fall time | t _f | | - | 72 | _ | 115 |
| | Turn-off time | t _{off} | | _ | 235 | _ | |
| Total gate charge (Gate-source plus gate-drain) | | Qg | | _ | 90 | | _ |
| Gate-source charge | | Q _{gs} | $V_{DD} \approx 24 \text{ V, } V_{GS} = 10 \text{ V, } I_D = 13 \text{ A}$ | _ | 60 | _ | nC |
| Gate-drain ("miller") charge | | Q_{gd} | | | 30 | _ | |

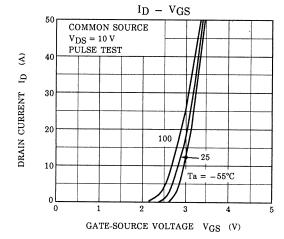
Source-Drain Ratings and Characteristics (Ta = 25°C)

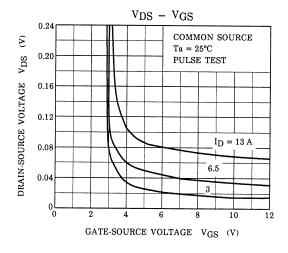
| Charact | teristics | Symbol | Test Condition | Min | Тур. | Max | Unit |
|-------------------------|----------------|------------------|---|-----|------|------|------|
| Drain reverse current | Pulse (Note 1) | I _{DRP} | _ | _ | _ | 52 | Α |
| Forward voltage (diode) | | V _{DSF} | I _{DR} = 13 A, V _{GS} = 0 V | _ | _ | -1.2 | V |

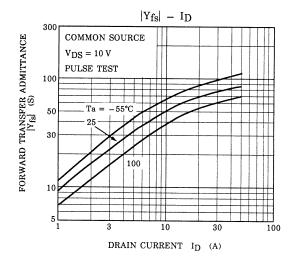
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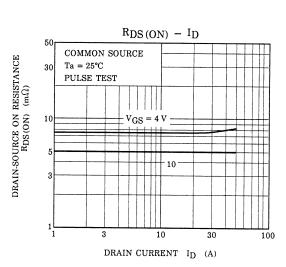




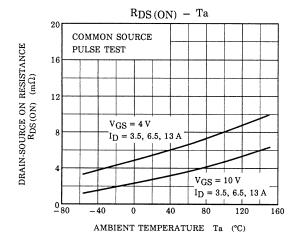


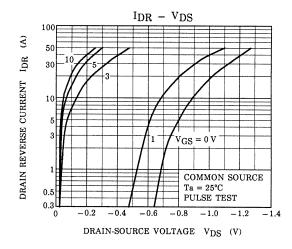


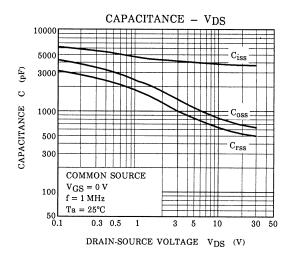


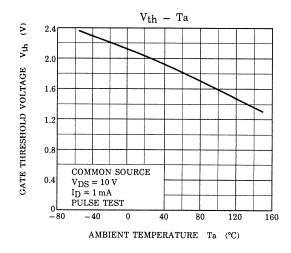


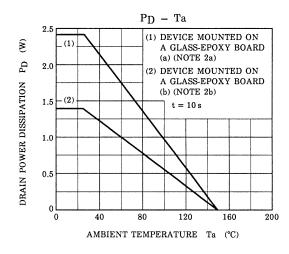
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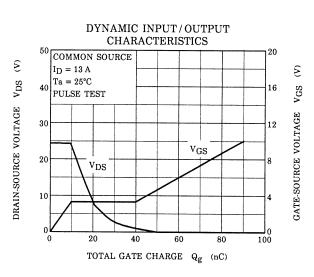


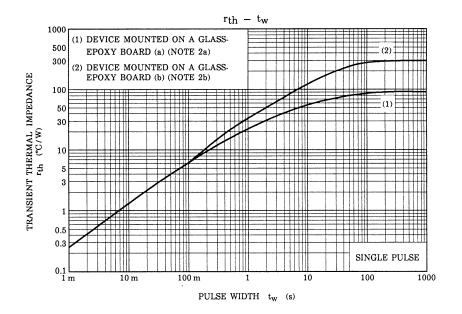


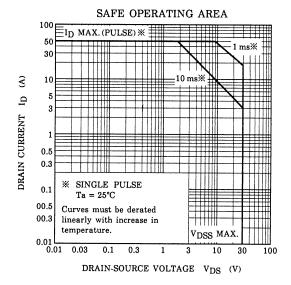


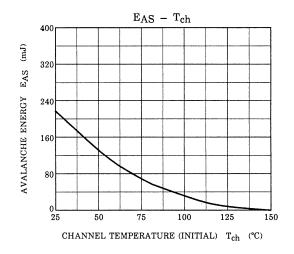


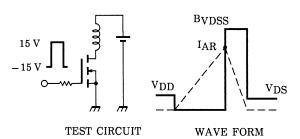












$$\begin{array}{ll} T_{ch} = 25^{\circ}\text{C (Initial)} \\ \text{Peak I}_{AR} = 13 \text{ A, R}_{G} = 25 \, \Omega \end{array} \quad \text{E}_{AS} = \frac{1}{2} \cdot \text{L} \cdot \text{I}^{2} \cdot (\frac{\text{BVDSS}}{\text{BVDSS} - \text{VDD}}) \\ \text{V}_{DD} = 24 \, \text{V, L} = 1.0 \, \text{mH} \end{array}$$

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